

## General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Z series is integrated with fast recovery diode (FRD) to minimize reverse recovery time. It is suitable for resonant switching topologies to reach higher efficiency, higher reliability and smaller form factor.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity



## Applications

- LED lighting
- Adapter
- Telecom
- Solar/UPS
- Server

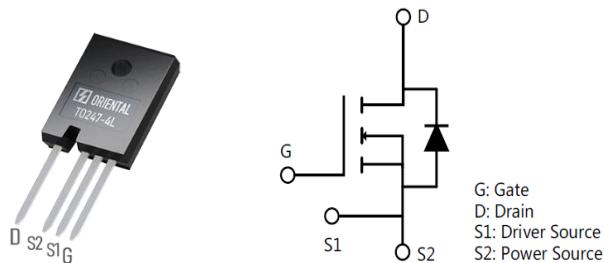
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	700	V
$I_D, pulse$	330	A
$R_{DS(ON), max} @ V_{GS}=10V$	22	mΩ
$Q_g$	204	nC

## Marking Information

Product Name	Package	Marking
OSG65R022H4T3ZF	TO247-4L	OSG65R022H4T3Z

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	650	V
Gate-source voltage	$V_{GS}$	$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_D$	110	A
Continuous drain current <sup>1)</sup> , $T_C=100\text{ }^\circ\text{C}$		69.6	
Pulsed drain current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_{D,\text{pulse}}$	330	A
Continuous diode forward current <sup>1)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_S$	110	A
Diode pulsed current <sup>2)</sup> , $T_C=25\text{ }^\circ\text{C}$	$I_{S,\text{pulse}}$	330	A
Power dissipation <sup>3)</sup> , $T_C=25\text{ }^\circ\text{C}$	$P_D$	652	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	2250	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\text{...}400\text{ V}$	dv/dt	100	V/ns
Reverse diode dv/dt, $V_{DS}=0\text{...}400\text{ V}$ , $I_{SD}\leq I_D$	dv/dt	50	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.19	$^\circ\text{C/W}$
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	$^\circ\text{C/W}$

**Electrical Characteristics** at  $T_j=25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	650			V	$V_{GS}=0\text{ V}$ , $I_D=2\text{ mA}$
		700				$V_{GS}=0\text{ V}$ , $I_D=2\text{ mA}$ , $T_j=150\text{ }^\circ\text{C}$
Gate threshold voltage	$V_{GS(\text{th})}$	3.0		5.0	V	$V_{DS}=V_{GS}$ , $I_D=2\text{ mA}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		18	22	$\text{m}\Omega$	$V_{GS}=10\text{ V}$ , $I_D=55\text{ A}$
			45			$V_{GS}=10\text{ V}$ , $I_D=55\text{ A}$ , $T_j=150\text{ }^\circ\text{C}$
Gate-source leakage current	$I_{GS}$			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	$I_{DS}$			10	$\mu\text{A}$	$V_{DS}=650\text{ V}$ , $V_{GS}=0\text{ V}$
Gate resistance	$R_G$		1.1		$\Omega$	$f=1\text{ MHz}$ , Open drain

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C <sub>iss</sub>		10554		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =50 V, f=100 kHz
Output capacitance	C <sub>oss</sub>		526		pF	
Reverse transfer capacitance	C <sub>rss</sub>		5.2		pF	
Effective output capacitance, energy related	C <sub>o(er)</sub>		328		pF	V <sub>GS</sub> =0 V, V <sub>DS</sub> =0 V-400 V
Effective output capacitance, time related	C <sub>o(tr)</sub>		1960		pF	
Turn-on delay time	t <sub>d(on)</sub>		82		ns	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, R <sub>G</sub> =2 Ω, I <sub>D</sub> =50 A
Rise time	t <sub>r</sub>		124		ns	
Turn-off delay time	t <sub>d(off)</sub>		263		ns	
Fall time	t <sub>f</sub>		6		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q <sub>g</sub>		204		nC	V <sub>GS</sub> =10 V, V <sub>DS</sub> =400 V, I <sub>D</sub> =50 A
Gate-source charge	Q <sub>gs</sub>		64.9		nC	
Gate-drain charge	Q <sub>gd</sub>		66.3		nC	
Gate plateau voltage	V <sub>plateau</sub>		6.4		V	

### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V <sub>SD</sub>			1.3	V	I <sub>S</sub> =110 A, V <sub>GS</sub> =0 V
Reverse recovery time	t <sub>rr</sub>		232		ns	
Reverse recovery charge	Q <sub>rr</sub>		1.5		uC	
Peak reverse recovery current	I <sub>rrm</sub>		12		A	

### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R<sub>θJA</sub> is measured with the device mounted on 1 in square FR-4 board with 2oz. Copper, in a still air environment with T<sub>a</sub>=25 °C.
- 5) V<sub>DD</sub>=100 V, V<sub>GS</sub>=10 V, L=80 mH, starting T<sub>j</sub>=25 °C.

## Electrical Characteristics Diagrams

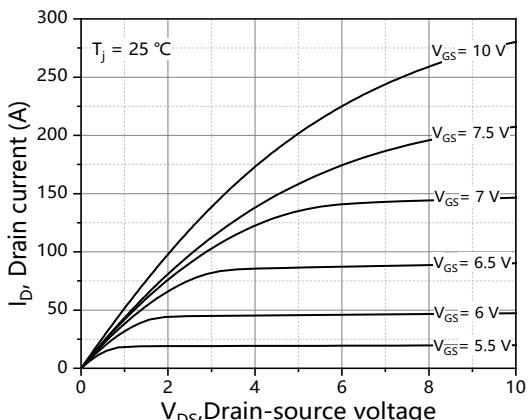


Figure 1. Typ. output characteristics

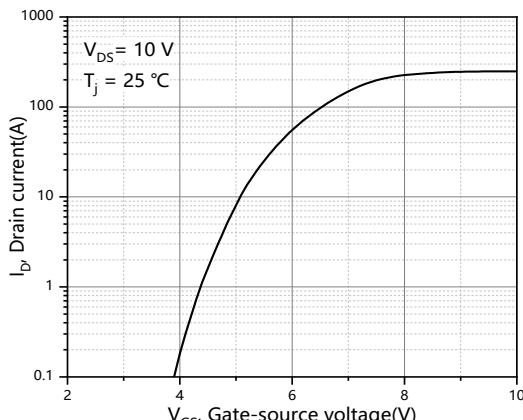


Figure 2. Typ. transfer characteristics

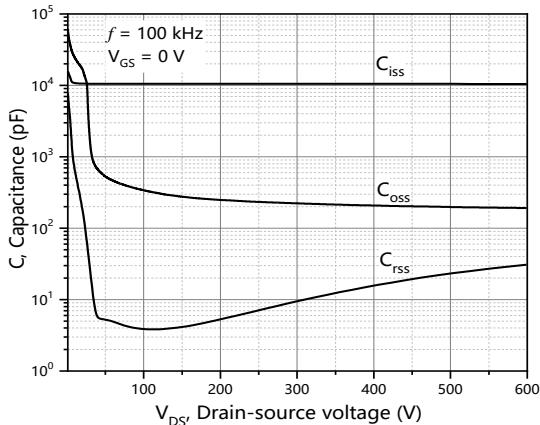


Figure 3. Typ. capacitances

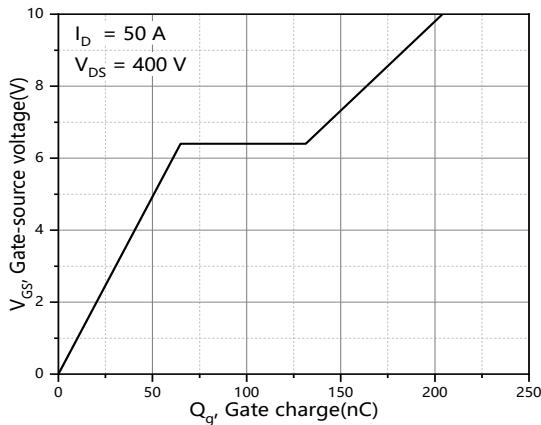


Figure 4. Typ. gate charge

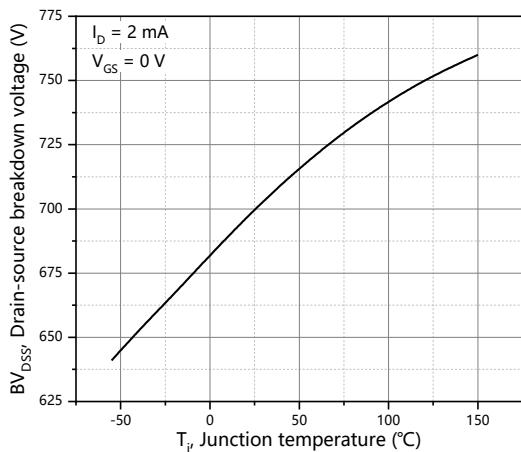


Figure 5. Drain-source breakdown voltage

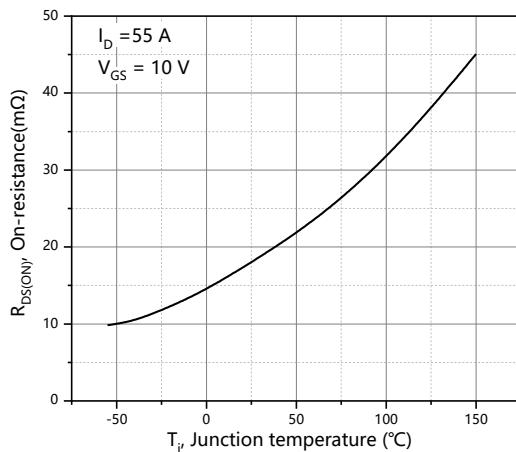
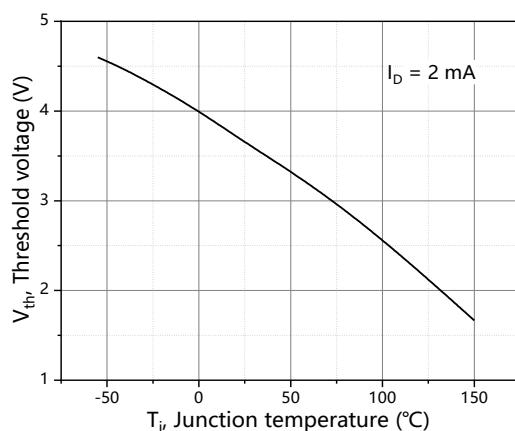
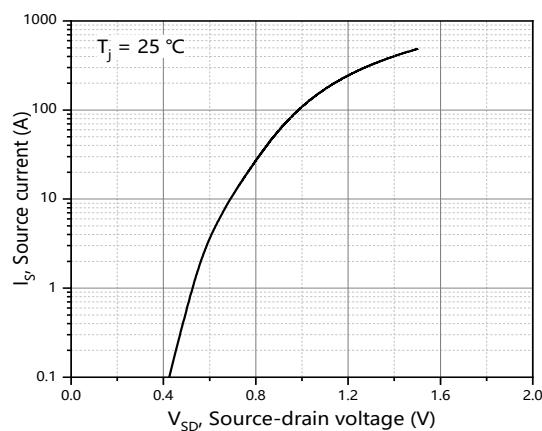
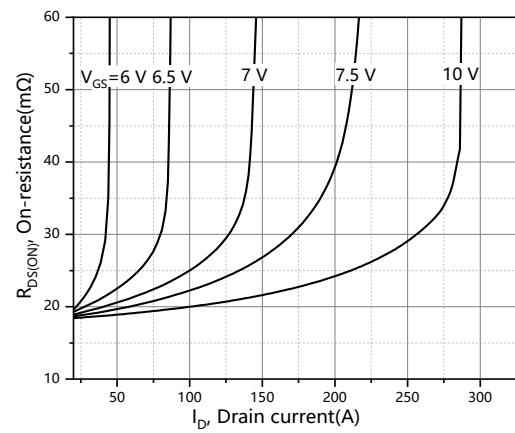
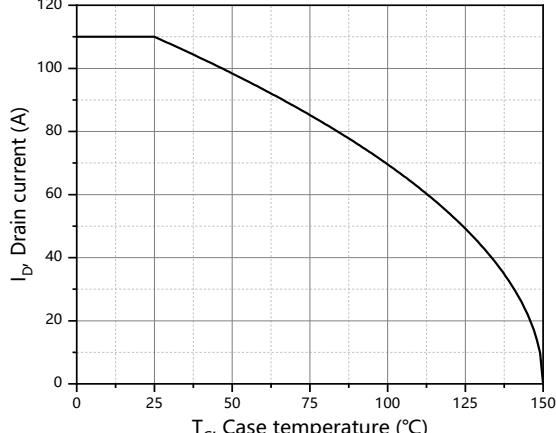
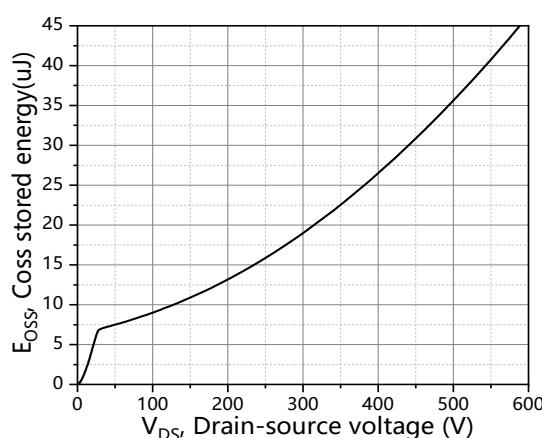
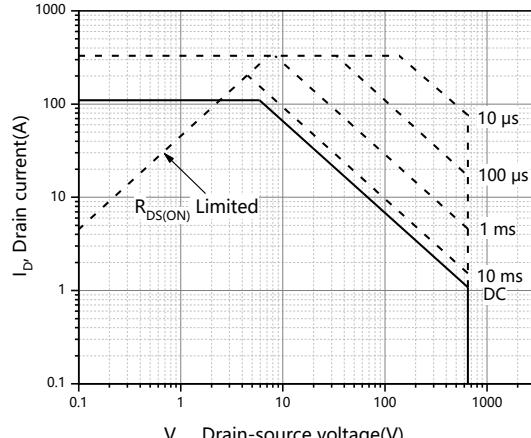


Figure 6. Drain-source on-state resistance


**Figure 7. Threshold voltage**

**Figure 8. Forward characteristic of body diode**

**Figure 9. Drain-source on-state resistance**

**Figure 10. Drain current**

**Figure 11. Typ. Coss stored energy**

**Figure 12. Safe operation area  $T_c=25$  °C**

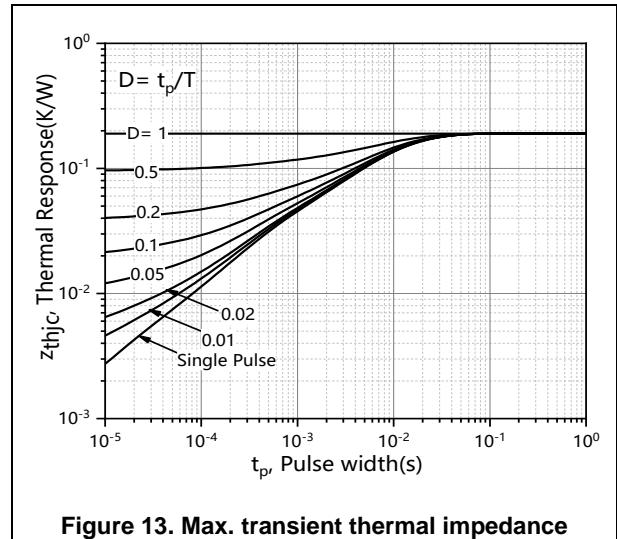


Figure 13. Max. transient thermal impedance

### Test circuits and waveforms

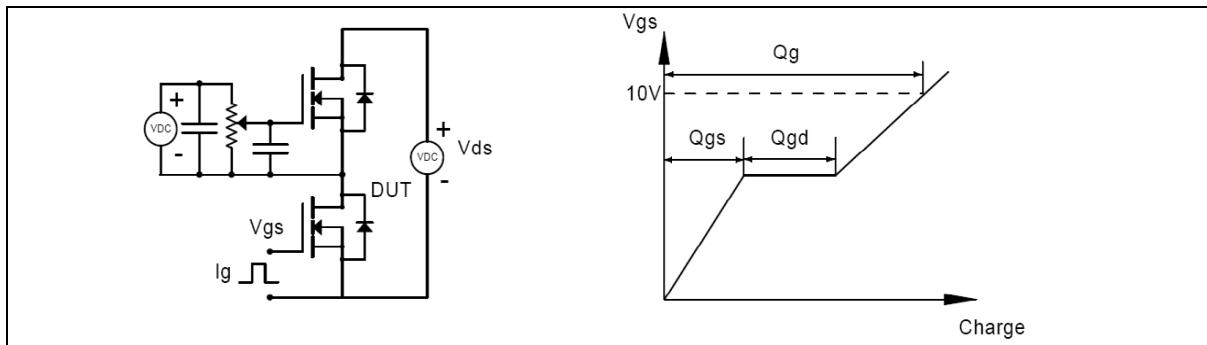


Figure 1. Gate charge test circuit & waveform

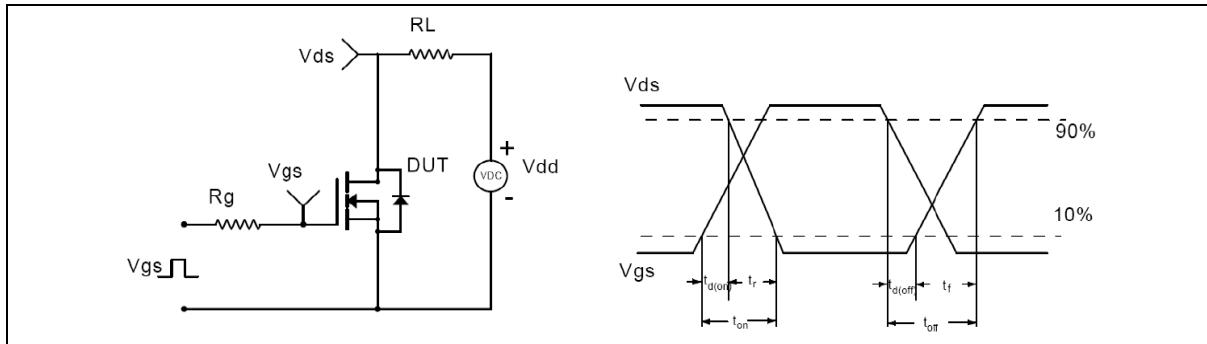


Figure 2. Switching time test circuit & waveforms

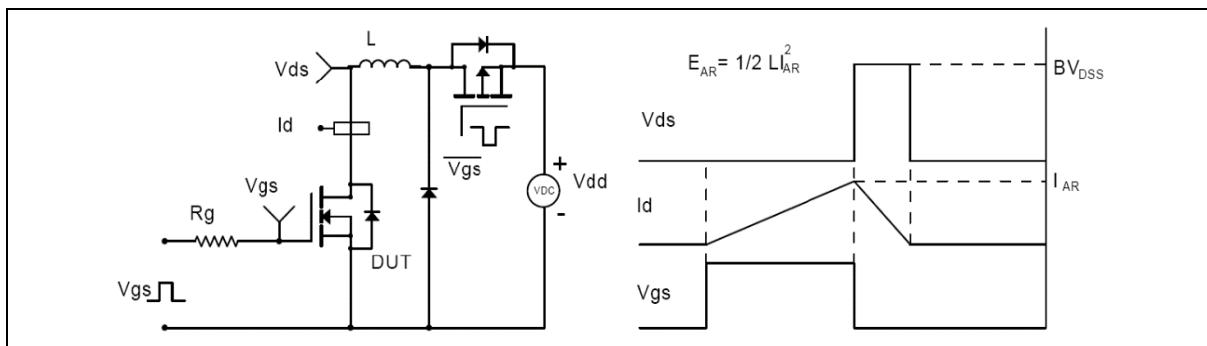


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

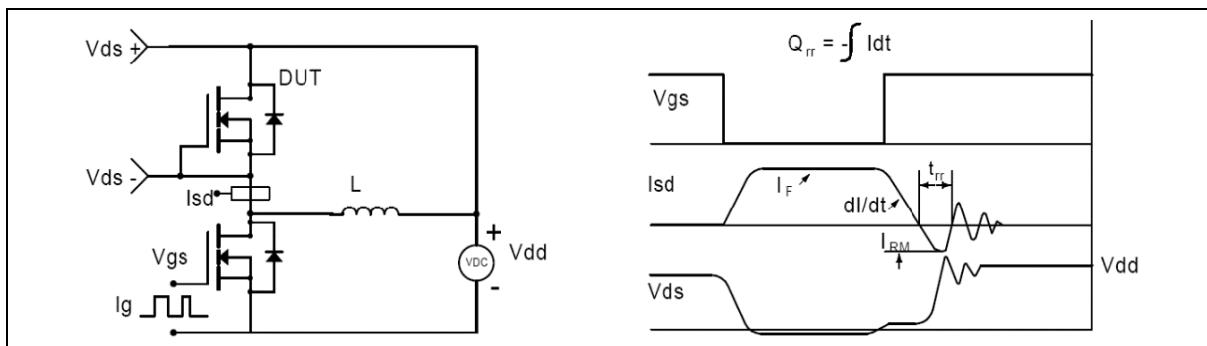
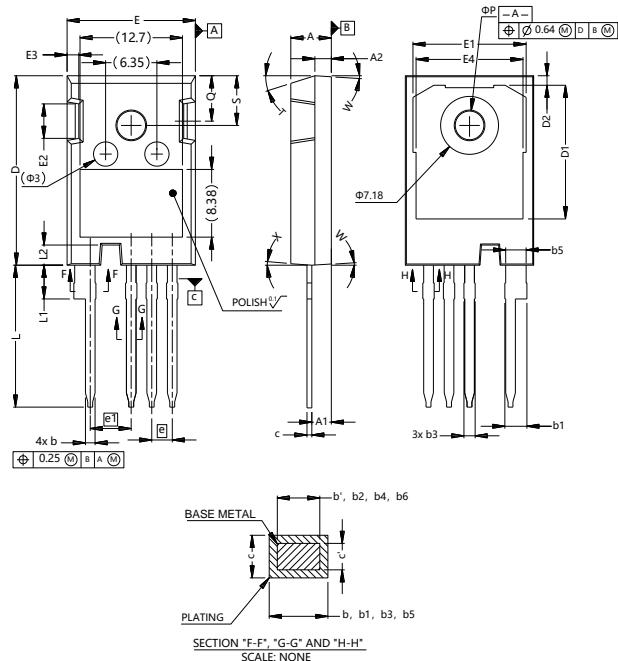


Figure 4. Diode reverse recovery test circuit & waveforms

## Package Information



Symbol	mm	
	Min	Max
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	2.39	2.94
b2	2.39	2.84
b3	1.07	1.60
b4	1.07	1.50
b5	2.39	2.69
b6	2.39	2.64
c'	0.55	0.65
c	0.55	0.68
D	23.30	23.60
D1	16.25	17.65
D2	0.95	1.25
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	2.54 BSC	
e1	5.08 BSC	
N	4	
L	17.31	17.82
L1	3.97	4.37
L2	2.35	2.65
ΦP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
T	17.5° REF	
W	3.5° REF	
X	4° REF	

Version: TO247-4L-S package outline dimension

## Ordering Information

Package Type	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO247-4L-S	30	15	450	4	1800

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG65R022H4T3ZF	TO247-4L	yes	yes	yes

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